

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









FAST CMOS 16-BIT TRANSPARENT LATCH

IDT74FCT16373AT/CT

FEATURES:

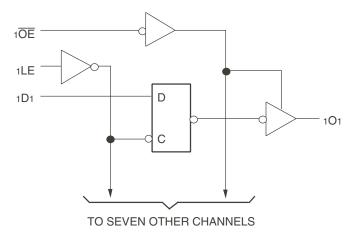
- 0.5 MICRON CMOS Technology
- . High-speed, low-power CMOS replacement for ABT functions
- Typical tsk(o) (Output Skew) < 250ps
- Low input and output leakage ≤1µA (max.)
- Vcc = 5V ±10%
- High drive outputs (-32mA IOH, 64mA IOL)
- Power off disable outputs permit "live insertion"
- Typical Volp (Output Ground Bounce) < 1.0V at Vcc = 5V, TA = 25°C
- Available in SSOP and TSSOP packages

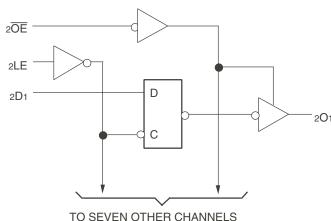
DESCRIPTION:

The FCT16373T 16-bit transparent D-type latch is built using advanced dual metal CMOS technology. These high-speed, low-power latches are ideal for temporary storage of data. They can be used for implementing memory address latches, I/O ports, and bus drivers. The Output Enable and Latch Enable controls are organized to operate each device as two 8-bit latches, or one 16-bit latch. Flow-through organization of signal pins simplifies layout. All inputs are designed with hysteresis for improved noise margin.

The FCT16373T is ideally suited for driving high-capacitance loads and low-impedance backplanes. The output buffers are designed with power off disable capability to allow "live insertion" of boards when used as backplane drivers.

FUNCTIONAL BLOCK DIAGRAM



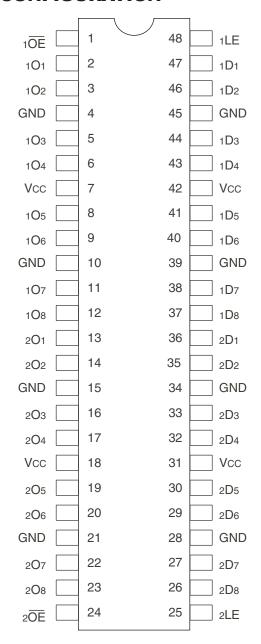


The IDT logo is a registered trademark of Integrated Device Technology, Inc.

INDUSTRIAL TEMPERATURE RANGE

SEPTEMBER 2009

PIN CONFIGURATION



SSOP/ TSSOP TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND -0.5 to 7		٧
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	٧
Tstg	Storage Temperature	-65 to +150	°C
Іоит	DC Output Current	-60 to +120	mA

NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. All device terminals except FCT162XXX Output and I/O terminals.
- 3. Outputs and I/O terminals for FCT162XXX.

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	3.5	6	рF
Соит	Output Capacitance	Vout = 0V	3.5	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description	
xDx	Data Inputs	
xLE	Latch Enable Input (Active HIGH)	
xŌĒ	Output Enable Input (Active LOW)	
хОх	3-State Outputs	

FUNCTION TABLE(1)

	Outputs		
хDх	xLE	xŌĒ	хОх
Н	Н	L	Н
L	Н	L	L
Х	Х	Н	Z

NOTE:

1. H = HIGH voltage level

L = LOW voltage level

X = Don't care

Z = High-impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

 $Following\ Conditions\ Apply\ Unless\ Otherwise\ Specified:$

Industrial: TA = -40°C to +85°C, VCC = 5.0V ± 10 %

Symbol	Parameter	Test Conditions	_S (1)	Min.	Typ. ⁽²⁾	Max.	Unit
VIH	Input HIGH Level	Guaranteed Logic HIGH Level		2	_	-	V
VIL	Input LOW Level	Guaranteed Logic LOW Level		_	_	0.8	V
Iн	Input HIGH Current (Input pins)(5)	Vcc = Max.	VI = VCC	_	_	±1	μA
	Input HIGH Current (I/O pins)(5)	1		_	_	±1	
lıL	Input LOW Current (Input pins)(5)	1	Vı = GND	T -	_	±1	
	Input LOW Current (I/O pins)(5)	1		_	_	±1	
lozh	High Impedance Output Current	Vcc = Max.	Vo = 2.7V	T -	_	±1	μА
lozL	(3-State Output pins) ⁽⁵⁾		Vo = 0.5V	-	_	±1	
VIK	Clamp Diode Voltage	Vcc = Min., IIN = -18mA		T -	-0.7	-1.2	V
los	Short Circuit Current	Vcc = Max., Vo = GND ⁽³⁾		-80	-140	-250	mA
VH	Input Hysteresis	_		T -	100	_	mV
ICCL	Quiescent Power Supply Current	Vcc = Max		T -	5	500	μA
ICCH		VIN = GND or Vcc					
Iccz							

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
lo	Output Drive Current	$Vcc = Max., Vo = 2.5V^{(3)}$		- 50	_	180	mA
Vон	Output HIGH Voltage	Vcc = Min.	Iон = –3mA	2.5	3.5	ı	V
		VIN = VIH or VIL	Iон = -15mA	2.4	3.5	ı	V
			IOH = -32mA ⁽⁴⁾	2	3	ı	V
Vol	Output LOW Voltage	Vcc = Min.	IoL = 64mA	_	0.2	0.55	V
		VIN = VIH or VIL					
IOFF	Input/Output Power Off Leakage ⁽⁵⁾	$VCC = 0V$, $VIN = or Vo \le 4.5V$	$VCC = 0V$, $VIN = or VO \le 4.5V$		_	±1	μА

- 1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
- 4. Duration of the condition can not exceed one second.
- 5. This test limit for this parameter is $\pm 5\mu A$ at $T_A = -55^{\circ} C$.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	Vcc = Max. $Vin = 3.4V^{(3)}$		_	0.5	1.5	mA
ICCD	Dynamic Power Supply Current ⁽⁴⁾	Vcc = Max. Outputs Open xOE = GND One Input Toggling 50% Duty Cycle	VIN = VCC VIN = GND	_	60	100	μΑ/ MHz
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max. Outputs Open fi = 10MHz 50% Duty Cycle xOE = GND xLE = Vcc	VIN = VCC VIN = GND VIN = 3.4V VIN = GND	_	0.6	2.3	mA
		One Bit Toggling Vcc = Max. Outputs Open	VIN = VCC VIN = GND	_	2.4	4.5 ⁽⁵⁾	
		fi = 2.5MHz 50% Duty Cycle xOE = GND xLE = Vcc Sixteen Bits Toggling	VIN = 3.4V VIN = GND	_	6.4	16.5 ⁽⁵⁾	

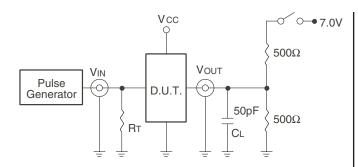
- 1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. Values for these conditions are examples of the lcc formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
 - $IC = ICC + \Delta ICC DHNT + ICCD (fcpNcp/2 + fiNi)$
 - Icc = Quiescent Current (IccL, Iccн and Iccz)
 - Δlcc = Power Supply Current for a TTL High Input (VIN = 3.4V)
 - DH = Duty Cycle for TTL Inputs High
 - NT = Number of TTL Inputs at DH
 - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 - fcp = Clock Frequency for Register Devices (Zero for Non-Register Devices)
 - NCP = Number of Clock Inputs at fCP
 - fi = Input Frequency
 - Ni = Number of Inputs at fi

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

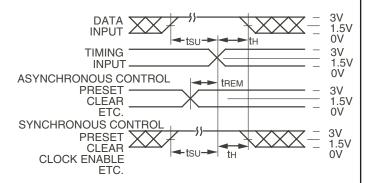
			FCT16	373AT	FCT16	6373CT	
Symbol	Parameter	Condition ⁽²⁾	Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	Unit
tplh	Propagation Delay	CL = 50pF	1.5	5.2	1.5	3.6	ns
tPHL	xDx to xOx	$RL = 500\Omega$					
tplh	Propagation Delay		2	8.5	2	3.7	ns
tPHL	xLE to xOx						
tpzh	Output Enable Time		1.5	6.5	1.5	4.4	ns
tpzl							
tPHZ	Output Disable Time		1.5	5.5	1.5	3.9	ns
tPLZ							
tsu	Set-up Time HIGH or LOW, xDx to xLE		2	_	2	_	ns
1H	Hold Time HIGH or LOW, xDx to xLE		1.5	_	1.5	_	ns
tw	xLE Pulse Width HIGH		5	_	5	_	ns
tsk(o)	Output Skew ⁽³⁾		_	0.5	_	0.5	ns

- 1. See test circuit and waveforms.
- 2. Minimum limits are guaranteed but not tested on Propagation Delays.
- 3. Skew between any two outputs, of the same package, switching in the same direction. This parameter is guaranteed by design.

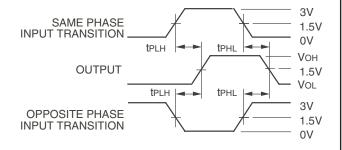
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



Propagation Delay

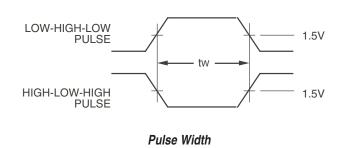
SWITCH POSITION

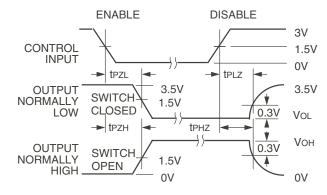
Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to ZouT of the Pulse Generator.

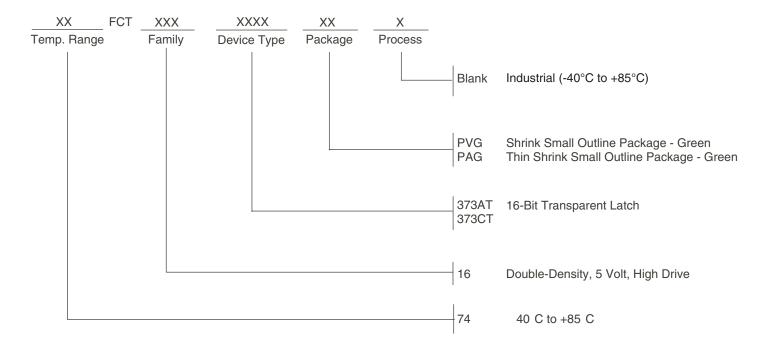




Enable and Disable Times

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tF \leq 2.5ns; tR \leq 2.5ns.

ORDERING INFORMATION



Datasheet Document History

09/10/09 Pg.7 Updated the ordering information by removing the "IDT" notation and non RoHS part.



CORPORATE HEADQUARTERS

6024 Silver Creek Valley Road San Jose, CA 95138

for SALES:

800-345-7015 or 408-284-8200 fax: 408-284-2775 www.idt.com

for Tech Support: logichelp@idt.com